

EAST - [default1.wsp:1]

File View Edit Tools Window Help

Drafts  
 ISNR:  
 Pending  
 Active  
 L1: (12) "5569852"  
 Failed  
 Saved  
 Favorites  
 Tagged (1)

Search  
 USPAT, USPGPUB, EPD, JPD, DERWENT  
 Default operator: OR  
 Highlight all hit terms initially

"5569852"

BRS L... ESR... Image Text HTML

	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6291875 B1	20010918	15	Microfabricated structures with electrical isolation	257/622	257/499
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6240782 B1	20010605	26	Semiconductor physical quantity sensor and	73/514.32	361/280; 73/514.18
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6227050 B1	20010508	33	Semiconductor mechanical sensor and method of	73/514.32	361/283.3; 73/504.15
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6199430 B1	20010313	61	Acceleration sensor with ring-shaped movable	73/514.32	73/514.36
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6087701 A	20000711	7	Semiconductor device having a cavity and method of	257/414	257/415; 257/419
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6070464 A	20000606	7	Sensing structure comprising a movable mass and a	73/514.32	73/1.38; 73/862.626
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6032532 A	20000307	8	Sensor, in particular accelerometer, and actuator	73/514.32	73/514.38
8	<input type="checkbox"/>	<input type="checkbox"/>	US 5780739 A	19980714	9	Tuning fork type gyroscope	73/504.16	
9	<input type="checkbox"/>	<input type="checkbox"/>	US 5703293 A	19971230	6	Rotational rate sensor with two acceleration sensors	73/504.02	73/504.12; 73/510
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5569852 A	19961029	5	Capacitive accelerometer sensor and method for its	73/514.32	361/280; 73/514.16
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5569852 A	19961029	5	Capacitive accelerometer sensor and method for its		

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DB: USPAT, US-PGPUB

Default operator: OR

accelerometer adj sensor

Display

Highlight all hit terms initially

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Import

Text

HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	R
1	<input type="checkbox"/>	<input type="checkbox"/>	US 5747353 A	19980505	16	Method of making surface micro-machined accelerometer	438/50	148/DIG. 135	

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File View Edit Tools Window Help

☐ Drafts  
☒ BRS:  
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☒ L1: (17) micromachine and trench and ICP  
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☐ Trash

☒ Plurals

Default operator: 
☒ Highlight all hit terms initially

micromachine and trench and ICP

☒ BRS term
 ☒ IS&R term
 ☐ Image
 ☐ Text
 ☐ HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	I
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20020190319 A1	20021219	14	Method for microfabricating structures using silicon-on-insulator material	257/347		
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20020187422 A1	20021212	8	Antireflective silicon-containing compositions as hardmask layer	430/270.1	430/272.1; 430/280.1;	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6581640 B1	20030624	15	Laminated manifold for microvalve	137/833	216/41; 216/56;	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6540203 B1	20030401	44	Pilot operated microvalve device	251/26	251/129.01; 251/129.07	
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6533554 B1	20030318	11	Thermal transpiration pump	417/207	417/48; 417/53	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6503692 B2	20030107	7	Antireflective silicon-containing compositions as hardmask layer	430/310		
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6494804 B1	20021217	12	Microvalve for electronically controlled transmission	475/127	137/625.6; 475/138	
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6420088 B1	20020716	6	Antireflective silicon-containing compositions as hardmask layer	430/272.1	430/270.1; 430/950;	
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6420084 B1	20020716	9	Mask-making using resist having SIO bond-containing polymer	430/270.1	430/277.1; 430/278.1;	
10	<input type="checkbox"/>	<input type="checkbox"/>	US 6402301 B1	20020611	12	Ink jet printheads and methods therefor	347/63		
11	<input type="checkbox"/>	<input type="checkbox"/>	US 6392313 B1	20020521	89	Microturbomachinery	290/52	257/414; 310/40MM;	
12	<input type="checkbox"/>	<input type="checkbox"/>	US 6342430 B1	20020129	17	Trench isolation for micromechanical devices	438/424	257/E21.546; 438/421;	
13	<input type="checkbox"/>	<input type="checkbox"/>	US 6239473 B1	20010529	17	Trench isolation for micromechanical devices	257/419	257/254; 257/417;	
14	<input type="checkbox"/>	<input type="checkbox"/>	US 6133615 A	20001017	15	Photodiode arrays having minimized cross-talk between diodes	257/446	257/292; 257/466;	
15	<input type="checkbox"/>	<input type="checkbox"/>	US 5932940 A	19990803	92	Microturbomachinery	310/40MM	257/414; 257/415;	
16	<input type="checkbox"/>	<input type="checkbox"/>	US 5865938 A	19990202	10	Wafer chuck for inducing an electrical bias across wafer heterojunctions	156/345.51		
17	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5637189 A	19970610	10	Dry etch process control using electrically biased stop junctions	438/466	216/67; 216/79;	

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	U	1	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	F
<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6433401 B1	20020813	21	Microfabricated structures with trench-isolation using bonded-substrates	257/524	257/510	
<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6386032 B1	20020514	16	Micro-machined accelerometer with improved transfer characteristics	73/504.02	73/514.18; 73/514.32	
<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6313529 B1	20011106	19	Bump bonding and sealing a semiconductor device with solder	257/724	257/778; 257/780;	
<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6291875 B1	20010918	15	Microfabricated structures with electrical isolation and interconnections	257/622	257/499	
<input type="checkbox"/>	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6184052 B1	20010206	7	Process for manufacturing high-sensitivity capacitive and resonant integrated sensors,	438/51	257/E21.552; 257/E21.573;	